


1 Substrate: 2.36mm \pm 0.178mm [0.093" \pm 0.007"]
FR4/G10 or equivalent high temp material.
17 μ m [1/2 oz.] Cu clad. SnPb plating.

2 Solder ball: Eutectic Sn63Pb37

Description: Fine Pitch BGA Surface Mount Adaptor
169 position 0.5mm pitch surface mount land pattern to solder balls.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA169H-B-05 Drawing		Status: Released	Scale: 3:1	Rev: A
 <p>© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: S. Faiz		Date: 2/15/10	
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